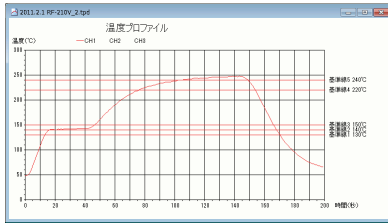
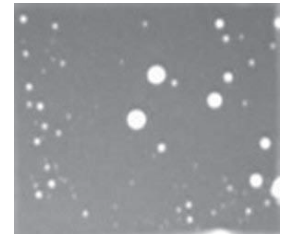


Voids free



Temperature Profile



Atmosphere Soldering



Vacuum Soldering

Vacuum Reflow Soldering Unit RF-210V

RF-210V allows soldering in high vacuum environment. This equipment is super low - cost vacuum reflow machine for experiments and/or prototype or small lot production.

Great for Power semiconductors, Power modules which have current devices that require keeping void to few percent below and this machine is able to perform void free soldering.

Features

Reflow soldering in under -95kPa G super-high vacuum environment

Compatible to Maximum 400°C 150mm × 150mm Work

This is 2 Zone by 1 Hotplate heating zone, 1 Cooling zone type vacuum soldering unit

Able to use Nitrogen(N₂) and Green Gas(Soldering in Gas Atmosphere)

Able to see while soldering in vacuum environment from observation window

Specifications

Heating Zone	: 1 Hotplate	150mm×150mm	1.1kW
	Direct heating from Hotplate underneath of Work		
Cooling Zone	: 1 Natural cooling Plate	150mm×150mm	
	Direct cooling from Cooling Plate underneath of Work		
Heating Temperature	: Max400°C		
Carrier System	: Carrier Bar(Push Work by Metal) system or 0.125mm Teflon Sheet (or 30μm SUS304 Sheet) carrier system		
Vacuum Source	: Vacuum Pump	Max -98kPa(G)	
Vacuum	: -95kPa(G) Time required; 150 sec. (Vacuum from atmosphere)		
Chamber	: (L)395×(W)340×(H)105mm		
	Work Area : (L)300×(W)150×(H)55mm		
Observation Window	: 105φ(Reflow part)		
Compatible Gas	: Gas Atmosphere Soldering : N ₂ or N ₂ +H ₂ (3-4%)		
Control	: Touch Panel type Sequencer		
Sensor Terminal	: Sensors for Temperature profile measurement terminal 3CH		
Safety	: Breaker for Leakage/Over current, Emergency Stop Switch		
Power source	: Single phase 200V/220V/240V	1.5kW	50/60Hz
External Dimension	: (W)600×(D)800×(H)860mm		
Weight	: Approximately 135kg		

Compatible Work

Max(W)150×(L)150×(H)50mm, Max300g
Metal or Ceramics with flat bottom

Intended Use

Tight bonding for Power semiconductor
Reflow Soldering for Power module
Soldering for Solar cell
Reflow Soldering for Metallic substrate



JAPAN PULSE LABORATORIES, INC.
425-3 Inari-cho, Isesaki-city, Gunma, 372-0804 Japan
Phone 0270-23-1031 Fax 0270-23-1943
<http://www.jpl.com/> info@jpl.com